



OVERVIEW

Designed for use in demanding environments where Size, Weight, and Power (SWAP) are severely limited, the Themis RES-mini server combines the robust design of the RES Server family using E5-2600 v2 Series Intel® Xeon® processors with up to twelve cores per processor. Fully compatible with popular virtualization technologies such as VMware and Citrix XenServer, the RES-mini brings next generation technology to mission-critical military, industrial, and commercial applications.

OPTIMIZED FOR SWAP-C

Featuring expansion slots, extensive high-speed I/O, and multiple storage options, the RES-mini server provides users with versatile configuration and system expansion options, and a strong, light-weight, coated aluminum chassis provides improved system resistance to corrosion.

The RES-mini also incorporates state-of-the-art thermal and kinetic management design. The addition of commercially available, off-the-shelf networking cards, graphics, I/O, peripherals, and other value-added options results in a system that has greater flexibility to meet current and future system requirements.

THEMIS VALUE

Themis provides systems integrators and end-users with the best-of-breed computing resources available, and works closely with them to optimize computing solutions that are easy to integrate, yet inexpensive to own and operate. For current information on Themis products, visit www.themis.com.

PROCESSOR AND CPU

- ▶ One E5-2600 v2 Series Intel® Xeon® processor with up to twelve cores per processor
- ▶ Up to 256 GB DDR3 ECC
- ▶ Eight, 2.5 inch drive bays

MECHANICAL

- ▶ Height: 4 inches (102 mm)
- ▶ Width: 13.5 inches (343 mm)
- ▶ Depth: 11 inches (278 mm)
- ▶ Weight: 15 lbs. (6.8 kg)

MANAGEMENT AND OPERATING SYSTEM

- ▶ Windows® and Linux® application support
- ▶ IPMI v2.0 support

ENVIRONMENTAL RESILIENCY

- ▶ Operating shock: 3 axis, 35g, 25ms
- ▶ Operating vibration: 4.76 Grms, 5 Hz to 2000 Hz
- ▶ Operating temperature: 0°C – Up to 55°C*
- ▶ Operating Humidity: 8% to 95% non-condensing

MODULAR MAINTAINABILITY

- ▶ Power supply options
 - Single 110/220 VAC (50/60Hz, 400Hz)
 - Single 28 VDC
 - Single 18 VDC
- ▶ Hot pluggable disk drives (8)

MILSPEC*

- ▶ MIL-STD-810G, MIL-S-901D, MIL-STD-167-1

* Themis designs all products to meet or exceed listed data sheet specifications. Some specifications are configuration dependant. Please contact Themis for information specific to your desired configuration requirements.



**PROCESSOR AND CPU**

PARAMETER	DESCRIPTION
Processor	One E5-2600 v2 Series Intel® Xeon® processor with up to twelve cores
Memory	Up to 256 GB DDR3 ECC

ON-BOARD EXPANSION

PARAMETER	QUANTITY	DESCRIPTION
Expansion slots	2, Note 1	Two PCI-E 3.0 x 16 slot for low-profile, half length cards

FRONT PANEL AND REAR PANEL ACCESS I/O, NOTE 2

I/O	Quantity	Access
Removable 2.5 SATA or SAS disk drives	Up to 8	Front panel
Status LEDs	5	Front panel
Power switch	1	Front panel
Gigabit Ethernet ports (RJ45)	2	Side panel
USB 2.0 ports	4	Side panel
RS-232 serial ports (DB9)	1 standard	Side panel
Power connector	1	Side panel
VGA Graphics	1	Side panel

ENVIRONMENTAL, NOTE 2

PARAMETER	NON-OPERATING	OPERATING
Temperature range	-40°C to 70°C	0°C to 55°C, Note 2
Extended Temperature Range	-40°C to 70°C	-15°C to 65°C, Note 3
Humidity	5% to 95% non-condensing	8% to 95%
Shock	3 axis, 35g at 25 ms	3 axis, 35g at 25 ms
Vibration (10-2000Hz)	3.0 Grms, 8 Hz to 2000 Hz	4.76 Grms, 5 Hz to 2000 Hz (SSD)

MODULAR MAINTAINABILITY

PARAMETER	DESCRIPTION
Hot pluggable disk drives	8
Power supply options	Single 110/220 VAC (50/60Hz, 400Hz) Single 28 VDC Single 18 VDC

MECHANICAL

PARAMETER	DESCRIPTION
Dimensions	Height: 4 inches (102 mm) Width: 13.5 inches (343 mm) Depth: 11 inches (278 mm)
Weight, Note 4	15 lbs (6.8 kg)
Chassis features	Coated aluminum for light weight and corrosion resistance Stainless steel in selected areas to add strength and stiffness Modular design for easy upgrade and service Optional rack-mount slides and shock pins Front to rear airflow

Notes

1. While there are two expansion slots, one of the slots is occupied by the storage controller with RAID.
2. Themis designs all products to meet or exceed listed data sheet specifications. Some specifications are configuration dependant. I/O options are configuration dependant.
2. Extended temperature range is dependant on system configuration/components and application thermal profile. Please contact Themis for information specific to your desired configuration.
3. Weights are provided for typical configurations. Weight may vary depending on configuration. Contact your Themis sales representatives for more information.

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